



Product Change Notice

Title	Change Notice for Dual Channel CompactFlash Modules
Affected Products	All Parts Starting with "CF-DC-G"
PCN#	12-0001
Date	April 27, 2012

Summary - Due to a die shrink by Samsung, WinSystems will be modifying the Heads/Cylinder/Sector (HCS) values for all of our dual-channel CompactFlash modules.

With this change WinSystems will also update the CompactFlash controller to support S.M.A.R.T. All other performance aspects will remain the same including the operational extended temperature range (-40C to +85C), advanced wear-leveling and SLC NAND-FLASH die.

Original HCS

CF-DC-G-1G-I = 2044/16/63 = 1055MB
CF-DC-G-2G-I = 4065/16/63 = 2098MB
CF-DC-G-4G-I = 8146/16/63 = 4204MB
CF-DC-G-8G-I = 16305/16/63 = 8415MB

New HCS

CF-DC-A-1G-I = 1986/16/63 = 1025MB
CF-DC-A-2G-I = 3875/16/63 = 2000MB
CF-DC-A-4G-I = 7751/16/63 = 4000MB
CF-DC-A-8G-I = 15501/16/63 = 8000MB

Impact: Customers may need to rebuild their master CompactFlash images to accommodate the change in size.

WinSystems Products Affected: The affected products are summarized in the table below:

Part Number	Description	Replacement
CF-DC-G-1G	1G Industrial CompactFlash	CF-DC-A-1G
CF-DC-G-2G	2G Industrial CompactFlash	CF-DC-A-2G
CF-DC-G-4G	4G Industrial CompactFlash	CF-DC-A-4G
CF-DC-G-8G	8G Industrial CompactFlash	CF-DC-A-8G

Effective Date: April 27, 2012

Recommended Action: Contact your WinSystems' Applications Engineer to start the re-qualification process.

Last Time Buy Schedule: Remaining inventory will be sold on a first-come-first serve basis

Last Time Ship Schedule: NC/NR Blanket orders will be accepted with a last ship date not to exceed 12/15/2013

Questions concerning this change: Call 817-274-7553
OR Contact your WinSystems' Applications Engineer.

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